



Material Content Data Sheet



Sales Product Name		TLE4998P8D		Issued		23. January 2018		
MA#		MA001677674						
Package		PG-TDSO-8-2		Weight*		68.12 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.883	5.70	5.70	57003	57003
leadframe	non noble metal	zinc	7440-66-6	0.064	0.09		945	
	non noble metal	tin	7440-31-5	0.080	0.12		1181	
	non noble metal	chromium	7440-47-3	0.097	0.14		1417	
wire	non noble metal	copper	7440-50-8	31.938	46.88	47.23	468824	472367
	noble metal	gold	7440-57-5	0.117	0.17	0.17	1715	1715
encapsulation	organic material	carbon black	1333-86-4	0.060	0.09		880	
	plastics	epoxy resin	-	3.238	4.75		47534	
	inorganic material	silicondioxide	60676-86-0	26.685	39.17	44.01	391715	440129
leadfinish	non noble metal	tin	7440-31-5	0.497	0.73	0.73	7299	7299
plating	noble metal	silver	7440-22-4	0.953	1.40	1.40	13983	13983
glue	plastics	acrylic resin	-	0.128	0.19		1876	
	plastics	epoxy resin	-	0.128	0.19		1876	
	inorganic material	silicondioxide	60676-86-0	0.256	0.38	0.76	3752	7504
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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